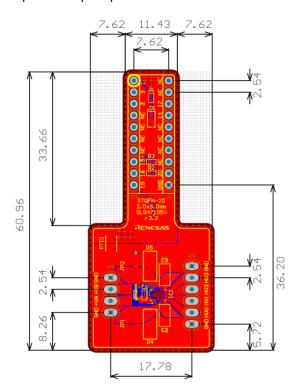


### 1. Description

The GreenPAK DIP Adapter is a small PCB that lets you adapt STQFN packages into a DIP footprint. This board can speed up your design prototyping and testing. This small board 0.90x2.20 inch uses 20 pins DIP footprint with 0.3 inch width. You can also use this adapter for prototyping by making STQFN package compatible with solder free breadboards.

### 2. Features

- Low cost
- Simplifies prototyping of SMT IC's
- Four high voltage high current output GPOs
- Current up to 1 A per HV GPO
- Current sensing resistors
  Variable current sensing configurations
- Optional V<sub>DD</sub> LED indicator
- Decoupling capacitor included
- Screw terminals for high voltage high and current lines
- Optional I<sup>2</sup>C pull-up resistors



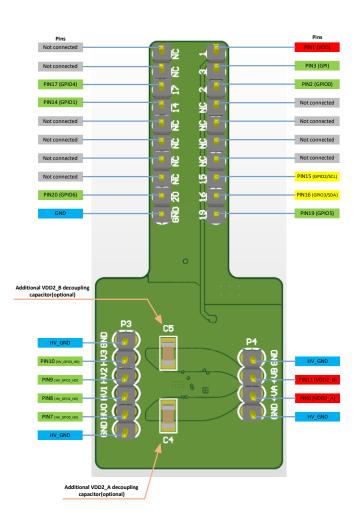
Note 1 All sizes in millimeters (mm).



# 3. Top View

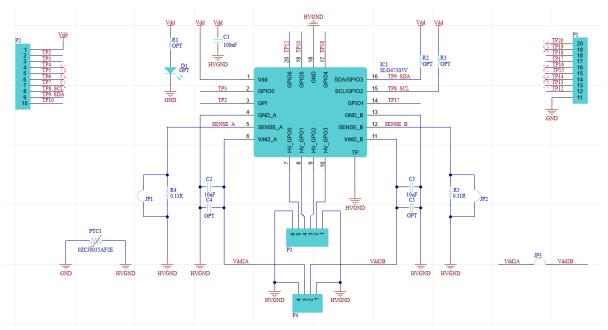
# VDD LED indicator (optional) PIN17 (GPIO4) PIN14 (GPIO1) Not connected Not connected Not connected Not connected Not connected 다. 13 13 13 13 13 13 PIN20 (GPIO6) PIN19 (GPIO5) Chip package type Chip package number VDD Chip decoupling capacitor SENSE B to GND (R5 BYPASS) GreenPAK chip R5 VDD2\_A to VDD2\_B solder jumper 2010 2010 SENSE\_A TO GND (R4 BYPASS) solder jumper VDD2\_A decoupling capacitor

### 4. Bottom View



## 5. Board Schematic

A PAIR OF SHUNT RESISTORS FOR VDD2 CIRCUIT



**Revision 1.2** 

26-Mar-2024

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